REMARKS

By this Amendment, claims 5-9 are amended, and claim 10 is added. Claims 2-4 and 6-8 remain in the application. Thus, claims 2-10 are active in the application. Reexamination and reconsideration of the application are respectfully requested.

The Applicant notes that the Examiner again failed to acknowledge, in item 12 on the Office Action Summary form, the Applicant's claim of foreign priority based on Japanese Patent Application No. 314581/2003, filed on September 5, 2003, and the receipt of the certified copy of the foreign priority document. A Claim of Priority and the certified copy of the foreign priority document were filed with the present application on January 26, 2004, and a courtesy copy of the January 26, 2004 Claim of Priority was submitted with the January 10, 2006 Amendment.

Accordingly, the Applicant respectfully requests the Examiner to acknowledge the Applicant's claim of foreign priority and the receipt of the certified copy of the foreign priority document.

A Request for Continued Examination (RCE), Information Disclosure Statement, Form PTO-1449, Japanese Office Action and a reference cited therein are submitted concurrently herewith. An English language translation of the Japanese Office Action is also submitted herewith. The Japanese Office Action cited two references, JP 10-135401 and JP 48-15474. JP 48-15474 was previously made of record by the Applicant in the January 10, 2006 Information Disclosure Statement. Accordingly, only JP 10-135401 is cited on the Form PTO-1449 submitted herewith.

The Applicant thanks the Examiner for kindly allowing claims 2-4 on page 2 of the Office Action.

However, on page 2 of the Office Action, claims 5-7 were rejected under 35 U.S.C. § 102(b) as being anticipated by JP 7-30051.

Without intending to acquiesce to this rejection, independent claim 5 has been amended to more clearly illustrate the marked differences between the present invention and the applied reference. Accordingly, the Applicant respectfully submits that the invention of claim 5 is clearly patentable over the applied reference for the following reasons.

Claim 5 has been amended to recite that the lead frame of the semiconductor device has a plurality of arranged <u>single-piece</u> leads which each have an outer lead portion, a first inner lead portion and a second inner lead portion which is located between the first inner lead portion and the outer lead portion.

JP 7-30051 merely discloses a semiconductor device having outer lead portions 48 and inner lead portions 60, where the outer lead portions 48 are thicker and wider than the inner lead portions 60 (see Figure 5).

However, JP 7-30051 clearly does not disclose or suggest that the outer lead portion 48 and the inner lead portion 60 of a lead are formed in a <u>single-piece</u>.

Accordingly, JP 7-30051 clearly does not disclose or suggest a semiconductor device comprising a lead frame having a plurality of arranged <u>single-piece</u> leads which each have an outer lead portion, a first inner lead portion and a second inner lead portion which is located between the first inner lead portion and the outer lead portion, as recited in claim 5.

Furthermore, JP 7-30051 clearly does not disclose or suggest a semiconductor device comprising a first semiconductor element having a plurality of first electrodes which are respectively connected to the first inner lead portions of the plurality of <u>single-piece</u> leads by a bump, as recited in claim 5.

Moreover, JP 7-30051 clearly does not disclose or suggest a semiconductor device comprising a second semiconductor element having a plurality of second electrodes which are respectively connected to the second inner lead portions of the plurality of single-piece leads by a wire, as recited in claim 5.

Therefore, claim 5 is clearly not anticipated by JP 7-30051 since JP 7-30051 fails to disclose each and every limitation recited in claim 5.

Furthermore, in view of the clear distinctions between the invention of claim 5 and JP 7-30051, the Applicant respectfully submits that one skilled in the art would not have been motivated to modify JP 7-30051 in such a manner as to result in, or otherwise render obvious, the invention of claim 5.

Therefore, the Applicant respectfully submits that claim 5, as well as claims 6-10 which depend therefrom, are clearly patentable over JP 7-30051.

In view of the foregoing amendments and remarks, it is respectfully submitted that the present application is clearly in condition for allowance. An early notice thereof is respectfully solicited.

If, after reviewing this Amendment, the Examiner feels there are any issues remaining which must be resolved before the application can be passed to issue, the Examiner is respectfully requested to contact the undersigned by telephone in order to resolve such issues.

Respectfully submitted,

Sunji ICHIKAWA

By:

Jonathan R. Bowser

Registration No. 54,574

Attorney for Applicant

JRB/nrj Washington, D.C. 20006-1021 Telephone (202) 721-8200 Facsimile (202) 721-8250 April 28, 2006